Please replace the paragraph on page 3, starting on line 6, with the following replacement paragraph.

According to a preferred embodiment of the present invention, the reduced diameter portion has a smaller inner diameter than the outer diameter of the coil spring portion, and is provided at each axial end of the through hole, and the other of the pair of electrode pin portions has a cylindrical shape which has a smaller diameter than the reduced diameter portion. Thus, when the object to be contacted has a convex surface as is the case with a solder ball, the electrode pin portion having a cylindrical shape can be applied to the object to be contacted with a certain guiding action, and a stable contact with an object such as a solder ball can be achieved.

Please replace the paragraphs on page 4, starting on line 3, with the following replacement paragraphs.

Figure 1 is an enlarged sectional side view of an essential part of a socket for semiconductor devices embodying the present invention;

Figure 2(a) is a fragmentary perspective view of an essential part showing the coil wire which is gold plated;

Figure 2(b) is a view similar to Figure 2(a) showing the coil wire after it is closely wound;

Figure 2(c) is a view similar to Figure 2(b) showing the coil wire after it is gold plated once again;

Figure 3 is a view similar to Figure 1 showing the socket for semiconductor devices embodying the present invention during use;

Figure 4 is a view similar to Figure 1 showing a second embodiment of the present invention;

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Figure 5 is a view similar to Figure 3 showing the second embodiment of the present invention;

Figure 6 is a view showing a third embodiment of the present invention;

Figure 7(a) is a fragmentary perspective view of an essential part of a coil wire following a coiling process; and

Figure 7(b) is a similar view following a gold plating process.

Please replace the paragraph starting on page 6, line 20, with the following replacement paragraph.

When the two insulating plates 1 are assembled to be in close contact to each other by using threaded bolts or the like, the resilient force of the coil spring portion 4 pushes the tapered portions of the electrode pin portions 5a and 5b against the tapered surfaces of the corresponding tapered hole sections 2a which are complementary to the tapered portions of the electrode pin portions 5a and 5b. Owing to the engagement between the opposing tapered surfaces, the lateral shifting of the free ends of the electrode pin portions 5a and 5b can be favorably minimized. Therefore, when a plurality of such electroconductive contact units are arranged in a matrix as is the case with a socket, the projecting end of each electrode pin portion 5a or 5b can be arranged in a planar coordinate system at a high precision without any effort during the assembly work.

Please replace the paragraph starting on page 11, line 18, with the following replacement paragraph.

Because the tapered hole section 2a is not required to be formed, the forming and assembling processes are simplified. For instance, during a time period in which products of a same model are required to be tested, a same relay board may be kept integrally attached to

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